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74LCX245

Low Voltage Bidirectional Transceiver with 5V Tolerant Inputs and Outputs

Features

- 5V tolerant inputs and outputs
- 2.3V to 3.6V V_{CC} specifications provided
- 7.0ns t_{PD} max. ($V_{CC} = 3.3V$), 10 μ A I_{CC} max.
- Power down high impedance inputs and outputs
- Supports live insertion/withdrawal⁽¹⁾
- $\pm 24mA$ output drive ($V_{CC} = 3.0V$)
- Implements proprietary noise/EMI reduction circuitry
- Latch-up performance exceeds 500mA
- ESD performance:
 - Human body model > 2000V
 - Machine model > 200V
- Leadless DQFN package

Note:

1. To ensure the high-impedance state during power up or down, \overline{OE} should be tied to V_{CC} through a pull-up resistor: the minimum value of the resistor is determined by the current-sourcing capability of the driver.

General Description

The LCX245 contains eight non-inverting bidirectional buffers with 3-STATE outputs and is intended for bus oriented applications. The device is designed for low voltage (2.5V and 3.3V) V_{CC} applications with capability of interfacing to a 5V signal environment. The T/\overline{R} input determines the direction of data flow through the device. The \overline{OE} input disables both the A and B ports by placing them in a high impedance state.

The LCX245 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

Ordering Information

| Order Number | Package Number | Package Description |
|----------------------------|----------------|---------------------------------------------------------------------------------------------|
| 74LCX245WM | M20B | 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide |
| 74LCX245SJ | M20D | 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide |
| 74LCX245BQX ⁽²⁾ | MLP20B | 20-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 4.5mm |
| 74LCX245MSA | MSA20 | 20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide |
| 74LCX245MTC | MTC20 | 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide |

Note:

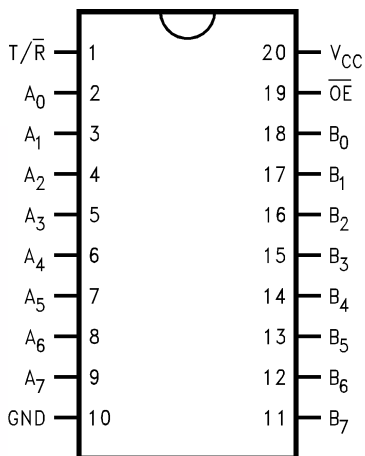
2. DQFN package available in Tape and Reel only.

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.

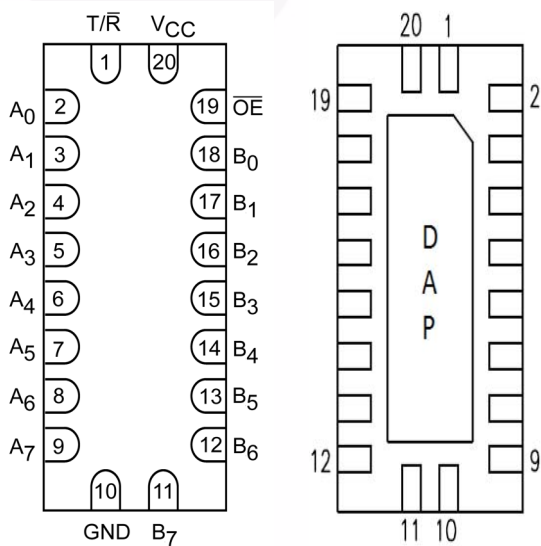
 All packages are lead free per JEDEC: J-STD-020B standard.

Connection Diagrams

Pin Assignments for SOIC, SOP, SSOP, and TSSOP



Pin Assignment for DQFN



(Top Through View)

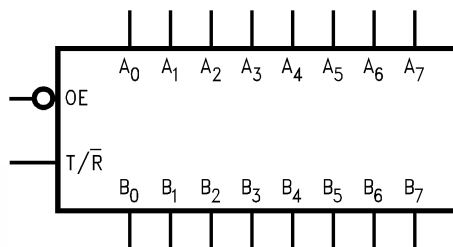
(Bottom View)

Pin Description

| Pin Names | Description |
|------------------|----------------------------------|
| \overline{OE} | Output Enable Input |
| T/\overline{R} | Transmit/Receive Input |
| A_0-A_7 | Side A Inputs or 3-STATE Outputs |
| B_0-B_7 | Side B Inputs or 3-STATE Outputs |
| DAP | No Connect |

Note: DAP (Die Attach Pad)

Logic Symbol



Truth Table

| Inputs | | Outputs |
|--------|------------------|-------------------------------------------------------|
| OE | T/\overline{R} | |
| L | L | Bus $B_0 - B_7$ Data to Bus $A_0 - A_7$ |
| L | H | Bus $A_0 - A_7$ Data to Bus $B_0 - B_7$ |
| H | X | HIGH Z State on $A_0 - A_7, B_0 - B_7$ ⁽³⁾ |

H = HIGH Voltage Level

L = LOW Voltage Level

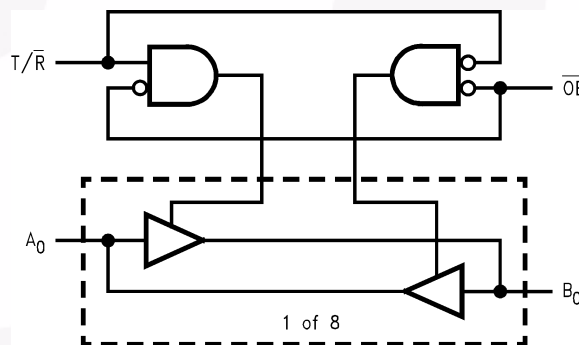
X = Immaterial

Z = High Impedance

Note:

3. Unused bus terminals during HIGH Z State must be held HIGH or LOW.

Logic Diagram



Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol | Parameter | Rating |
|-----------|--------------------------------------------|--------------------------|
| V_{CC} | Supply Voltage | -0.5V to +7.0V |
| V_I | DC Input Voltage | -0.5V to +7.0V |
| V_O | DC Output Voltage Output in 3-STATE | -0.5V to +7.0V |
| | Output in HIGH or LOW State ⁽⁴⁾ | -0.5V to $V_{CC} + 0.5V$ |
| I_{IK} | DC Input Diode Current, $V_I < GND$ | -50mA |
| I_{OK} | DC Output Diode Current $V_O < GND$ | -50mA |
| | $V_O > V_{CC}$ | +50mA |
| I_O | DC Output Source/Sink Current | $\pm 50mA$ |
| I_{CC} | DC Supply Current per Supply Pin | $\pm 100mA$ |
| I_{GND} | DC Ground Current per Ground Pin | $\pm 100mA$ |
| T_{STG} | Storage Temperature | -65°C to +150°C |

Note:

4. I_O Absolute Maximum Rating must be observed.

Recommended Operating Conditions⁽⁵⁾

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

| Symbol | Parameter | Min. | Max. | Units |
|-----------------------|---------------------------------------------------------|------|----------|-------|
| V_{CC} | Supply Voltage Operating | 2.0 | 3.6 | V |
| | Data Retention | 1.5 | 3.6 | |
| V_I | Input Voltage | 0 | 5.5 | V |
| V_O | Output Voltage 3-STATE | 0 | 5.5 | V |
| | HIGH or LOW State | 0 | V_{CC} | |
| I_{OH} / I_{OL} | Output Current $V_{CC} = 3.0V-3.6V$ | | ± 24 | mA |
| | $V_{CC} = 2.7V-3.0V$ | | ± 12 | |
| | $V_{CC} = 2.3V-2.7V$ | | ± 8 | |
| T_A | Free-Air Operating Temperature | -40 | 85 | °C |
| $\Delta t / \Delta V$ | Input Edge Rate, $V_{IN} = 0.8V-2.0V$, $V_{CC} = 3.0V$ | 0 | 10 | ns/V |

Note:

5. Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

| Symbol | Parameter | V _{CC} (V) | Conditions | T _A = -40°C to +85°C | | Units |
|------------------|---------------------------------------|---------------------|-----------------------------------------------------------------------------------|---------------------------------|------|-------|
| | | | | Min. | Max. | |
| V _{IH} | HIGH Level Input Voltage | 2.3–2.7 | | 1.7 | | V |
| | | 2.7–3.6 | | 2.0 | | |
| V _{IL} | LOW Level Input Voltage | 2.3–2.7 | | | 0.7 | V |
| | | 2.7–3.6 | | | 0.8 | |
| V _{OH} | HIGH Level Output Voltage | 2.3–3.6 | I _{OH} = -100μA | V _{CC} - 0.2 | | V |
| | | 2.3 | I _{OH} = -8mA | 1.8 | | |
| | | 2.7 | I _{OH} = -12mA | 2.2 | | |
| | | 3.0 | I _{OH} = -18mA | 2.4 | | |
| | | | I _{OH} = -24mA | 2.2 | | |
| V _{OL} | LOW Level Output Voltage | 2.3–3.6 | I _{OL} = 100μA | | 0.2 | V |
| | | 2.3 | I _{OL} = 8mA | | 0.6 | |
| | | 2.7 | I _{OL} = 12mA | | 0.4 | |
| | | 3.0 | I _{OL} = 16mA | | 0.4 | |
| | | | I _{OL} = 24mA | | 0.55 | |
| I _I | Input Leakage Current | 2.3–3.6 | 0 ≤ V _I ≤ 5.5V | | ±5.0 | μA |
| I _{OZ} | 3-STATE Output Leakage | 2.3–3.6 | 0 ≤ V _O ≤ 5.5V, V _I = V _{IH} or V _{IL} | | ±5.0 | μA |
| I _{OFF} | Power-Off Leakage Current | 0 | V _I or V _O = 5.5V | | 10 | μA |
| I _{CC} | Quiescent Supply Current | 2.3–3.6 | V _I = V _{CC} or GND | | 10 | μA |
| | | | 3.6V ≤ V _I , V _O ≤ 5.5V ⁽⁶⁾ | | ±10 | |
| ΔI _{CC} | Increase in I _{CC} per Input | 2.3–3.6 | V _{IH} = V _{CC} - 0.6V | | 500 | μA |

Note:

6. Outputs disabled or 3-STATE only.

AC Electrical Characteristics

| Symbol | Parameter | T _A = -40°C to +85°C, R _L = 500Ω | | | | | | Units |
|---------------------------------------|--------------------------------------------------------------------------------------------|---------------------------------------------------------|------|--------------------------------------------------|------|---------------------------------------------------------|------|-------|
| | | V _{CC} = 3.3V ± 0.3V, C _L = 50pF | | V _{CC} = 2.7V, C _L = 50pF | | V _{CC} = 2.5V ± 0.2V, C _L = 30pF | | |
| | | Min. | Max. | Min. | Max. | Min. | Max. | |
| t _{PHL} , t _{PLH} | Propagation Delay, A _n to B _n or B _n to A _n | 1.5 | 7.0 | 1.5 | 8.0 | 1.5 | 8.4 | ns |
| t _{PZL} , t _{PZH} | Output Enable Time | 1.5 | 8.5 | 1.5 | 9.5 | 1.5 | 10.5 | ns |
| t _{PLZ} , t _{PHZ} | Output Disable Time | 1.5 | 7.5 | 1.5 | 8.5 | 1.5 | 9.0 | ns |
| t _{OSHL} , t _{OSLH} | Output to Output Skew ⁽⁷⁾ | | 1.0 | | | | | ns |

Note:

7. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

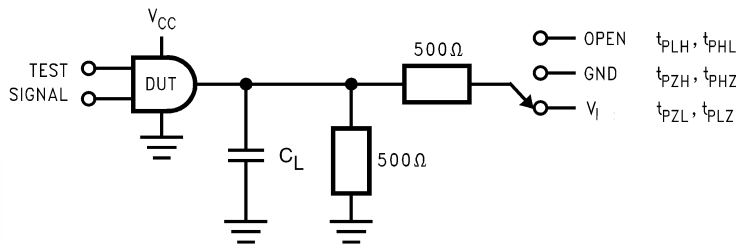
Dynamic Switching Characteristics

| Symbol | Parameter | V_{CC} (V) | Conditions | $T_A = 25^\circ\text{C}$ | |
|-----------|--------------------------------------|--------------|---------------------------------------------------------------|--------------------------|------|
| | | | | Typical | Unit |
| V_{OLP} | Quiet Output Dynamic Peak V_{OL} | 3.3 | $C_L = 50\text{pF}, V_{IH} = 3.3\text{V}, V_{IL} = 0\text{V}$ | 0.8 | V |
| | | 2.5 | $C_L = 30\text{pF}, V_{IH} = 2.5\text{V}, V_{IL} = 0\text{V}$ | 0.6 | |
| V_{OLV} | Quiet Output Dynamic Valley V_{OL} | 3.3 | $C_L = 50\text{pF}, V_{IH} = 3.3\text{V}, V_{IL} = 0\text{V}$ | -0.8 | V |
| | | 2.5 | $C_L = 30\text{pF}, V_{IH} = 2.5\text{V}, V_{IL} = 0\text{V}$ | -0.6 | |

Capacitance

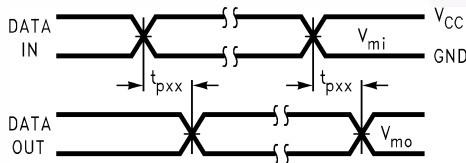
| Symbol | Parameter | Conditions | Typical | Units |
|-----------|-------------------------------|----------------------------------------------------------------------|---------|-------|
| C_{IN} | Input Capacitance | $V_{CC} = \text{Open}, V_I = 0\text{V or } V_{CC}$ | 7.0 | pF |
| C_{OUT} | Output Capacitance | $V_{CC} = 3.3\text{V}, V_I = 0\text{V or } V_{CC}$ | 8.0 | pF |
| C_{PD} | Power Dissipation Capacitance | $V_{CC} = 3.3\text{V}, V_I = 0\text{V or } V_{CC}, f = 10\text{MHz}$ | 25.0 | pF |

AC Loading and Waveforms (Generic for LCX Family)

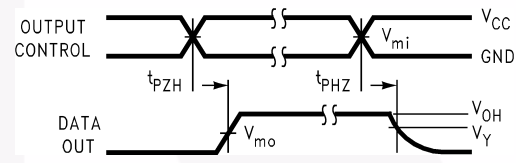


| Test | Switch |
|--------------------|-------------------------------------------------------------------------------|
| t_{PLH}, t_{PHL} | Open |
| t_{PZL}, t_{PLZ} | 6V at $V_{CC} = 3.3 \pm 0.3V$ $V_{CC} \times 2$ at $V_{CC} = 2.5 \pm 0.2V$ |
| t_{PZH}, t_{PHZ} | GND |

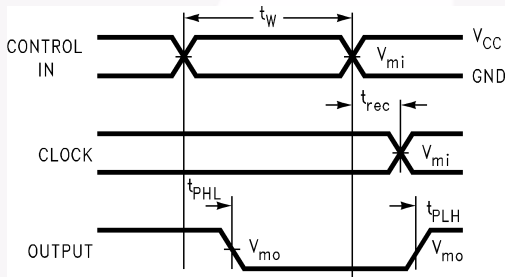
Figure 1. AC Test Circuit (C_L includes probe and jig capacitance)



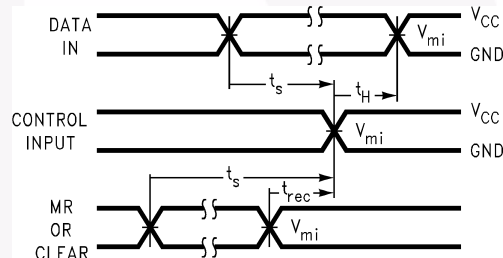
Waveform for Inverting and Non-Inverting Functions



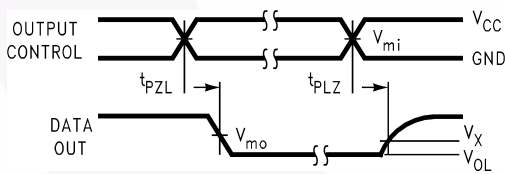
3-STATE Output High Enable and Disable Times for Logic



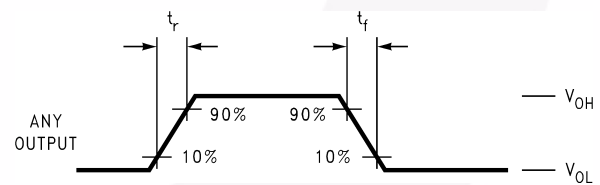
Propagation Delay, Pulse Width and t_{rec} Waveforms



Setup Time, Hold Time and Recovery Time for Logic



3-STATE Output Low Enable and Disable Times for Logic



t_{rise} and t_{fall}

| Symbol | V_{CC} | | |
|----------|-----------------|-----------------|------------------|
| | $3.3V \pm 0.3V$ | 2.7V | $2.5V \pm 0.2V$ |
| V_{mi} | 1.5V | 1.5V | $V_{CC}/2$ |
| V_{mo} | 1.5V | 1.5V | $V_{CC}/2$ |
| V_x | $V_{OL} + 0.3V$ | $V_{OL} + 0.3V$ | $V_{OL} + 0.15V$ |
| V_y | $V_{OH} - 0.3V$ | $V_{OH} - 0.3V$ | $V_{OH} - 0.15V$ |

Figure 2. Waveforms (Input Characteristics; $f = 1MHz, t_r = t_f = 3ns$)

Schematic Diagram (Generic for LCX Family)

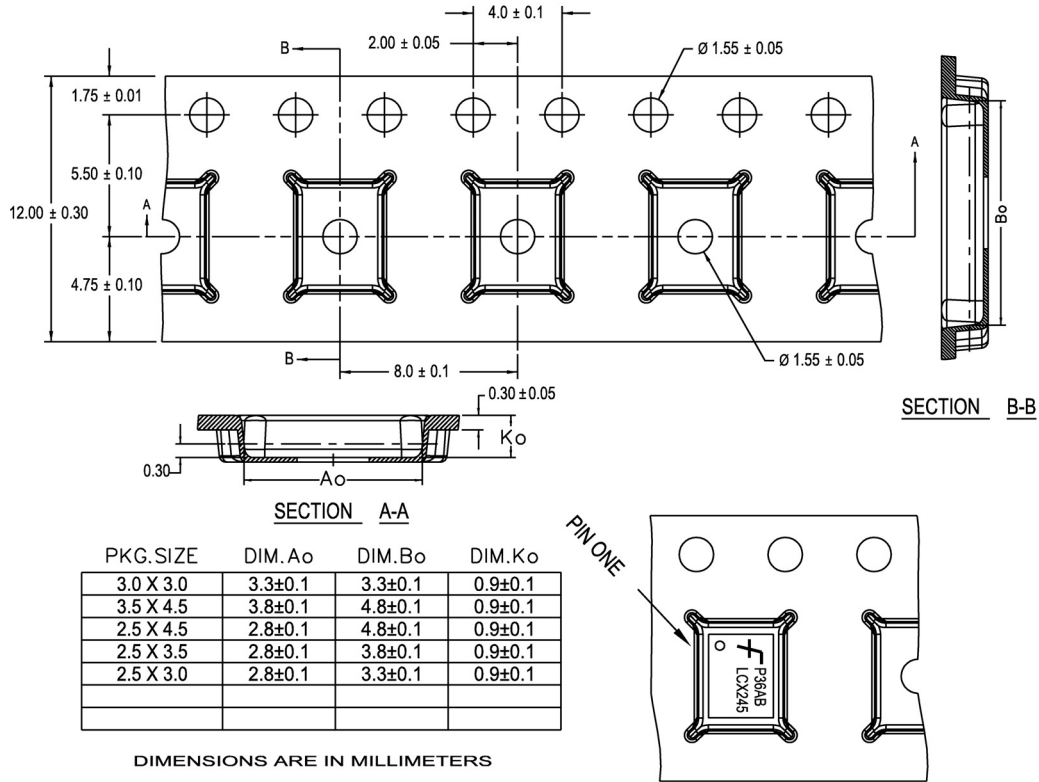


Tape and Reel Specification

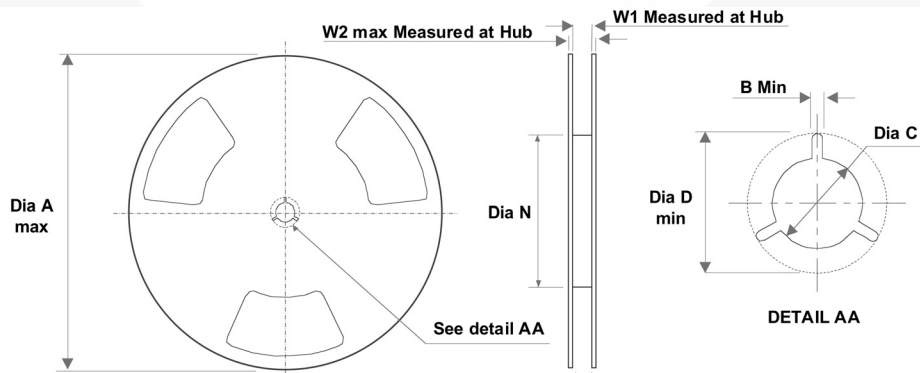
Tape Format for DQFN

| Package Designator | Tape Section | Number of Cavities | Cavity Status | Cover Tape Status |
|--------------------|--------------------|--------------------|---------------|-------------------|
| BQX | Leader (Start End) | 125 (typ.) | Empty | Sealed |
| | Carrier | 3000 | Filled | Sealed |
| | Trailer (Hub End) | 75 (typ.) | Empty | Sealed |

Tape Dimension inches (millimeters)



Reel Dimensions inches (millimeters)



| Tape Size | A | B | C | D | N | W1 | W2 |
|-----------|--------------|--------------|---------------|---------------|---------------|--------------|--------------|
| 12mm | 13.0 (330.0) | 0.059 (1.50) | 0.512 (13.00) | 0.795 (20.20) | 2.165 (55.00) | 0.488 (12.4) | 0.724 (18.4) |

Physical Dimensions

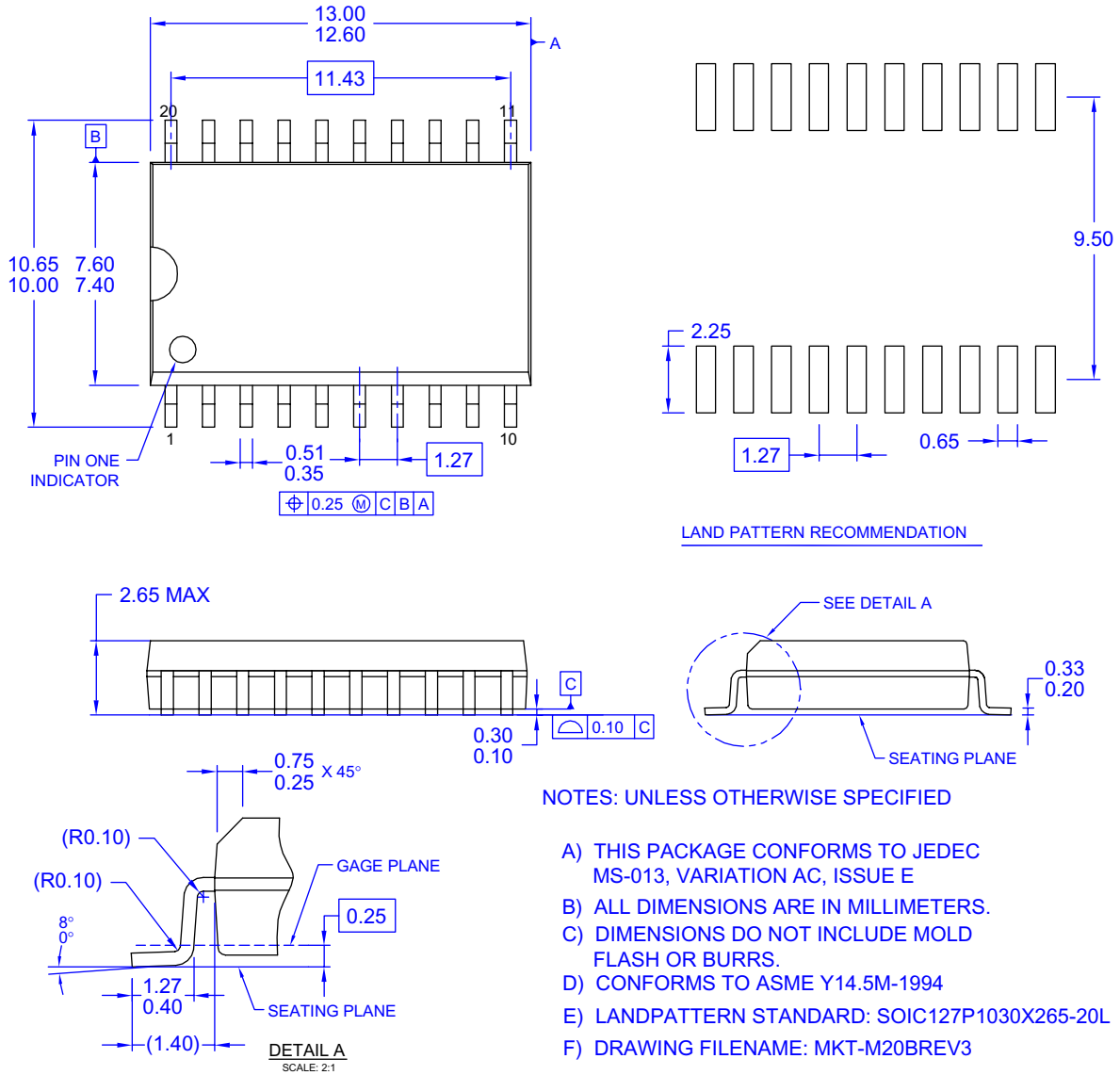


Figure 3. 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide

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Physical Dimensions (Continued)



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M20DREVC

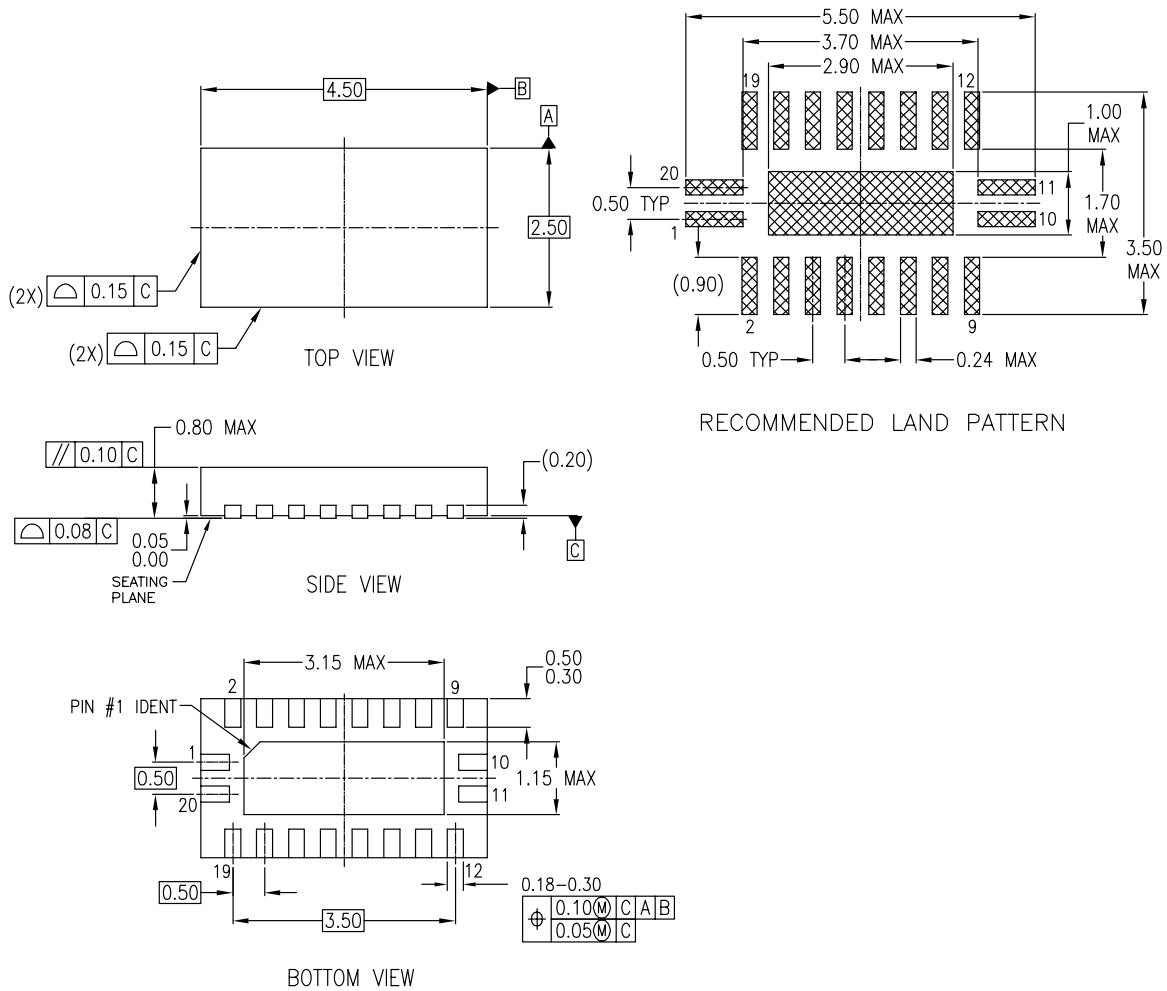
Figure 4. 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

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Physical Dimensions (Continued)



NOTES:

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- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

MLP20BrevA

Figure 5. 20-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 4.5mm

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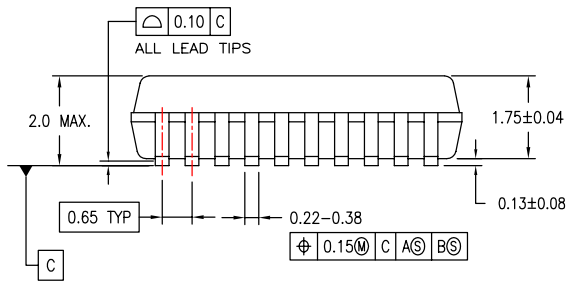
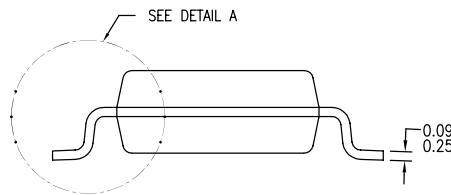
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Physical Dimensions (Continued)



LAND PATTERN RECOMMENDATIONS



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- D. DIMENSIONS AND TOLERANCES PER ASME Y14.5M - 1994.



MSA20REVB

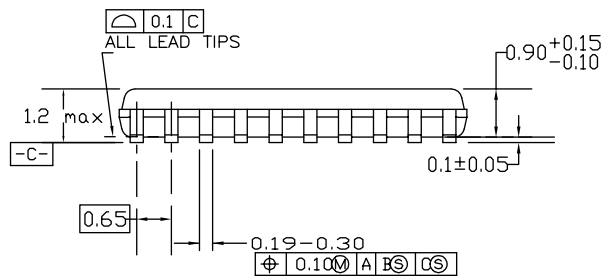
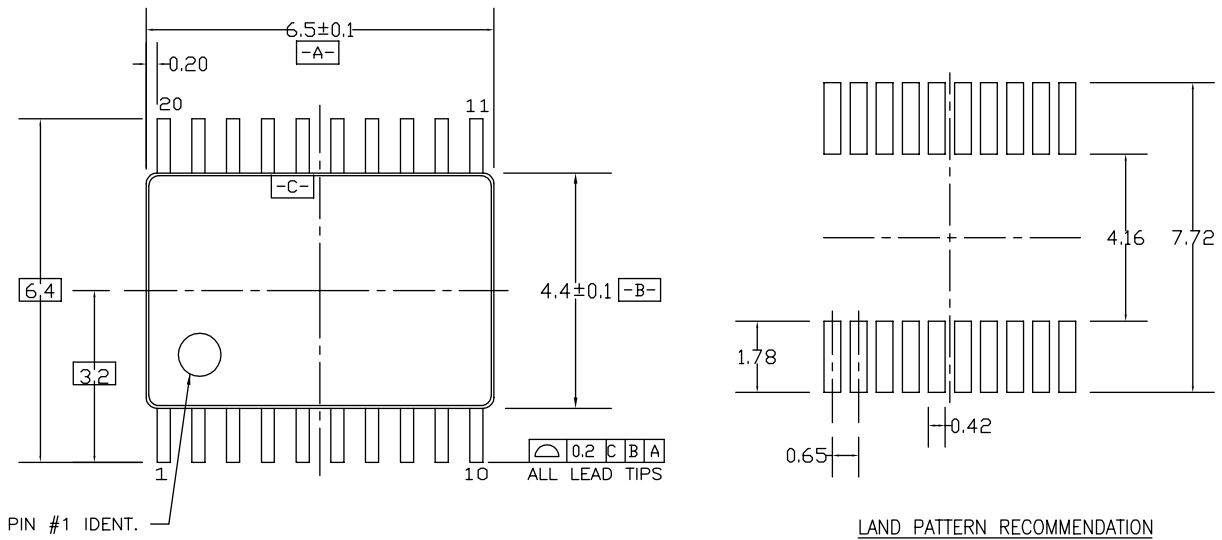
Figure 6. 20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide

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Physical Dimensions (Continued)



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- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC20REV D1

Figure 8. 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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| CorePLUS™ | Green FPS™ | Programmable Active Droop™ | TinyCalc™ |
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